

APPROVAL SHEET

WLPM505030 Series SMD Molded Power Inductor





*Contents in this sheet are subject to change without prior notice.



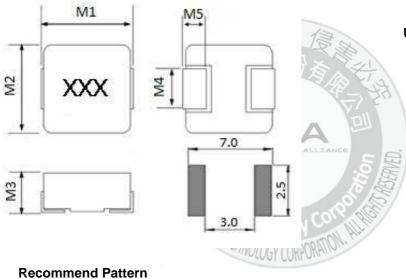
Features

- 1. Shielded construction.
- 2. Ultra low buzz noise.
- 3. Low DCR/µH.
- 4. Handles high transient current spikes without saturation.
- 5. Encapsulated body offers improved environmental protection and moisture resistance.
- 6. Higher dielectric withstanding voltage.
- 7. Corrosion resistant package.
- 8. RoHS Compliance.

Applications

- 1. PDA/Notebook/Desktop/Server applications high current and low profile power supplier
- 2. High current POL converters.
- 3. Battery powered devices.

SHAPE and DIMENSION



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	DIM.	TOL.
М1	4.85	±0.35
M2	4.7	±0.2
М3	2.8	±0.2
М4	1.5	±0.3
M5	1.0	±0.3

MARKING AND DATE CODE

Marking ex:1.0uH →1R0





Ordering Information

WL	PM	5050	30	М	R10	L	С
Product Code	Series	Dimensions	Thickness	Tolerance	Value	Packing Code	
WL: Inductor	SMD molded power inductor.	4.4 * 4.0mm	3.0 mm	M: ± 20%	1R0=1.0uH 100=10.0uH	L=13" Reeled (Embossed tape)	Internal code

Electrical Characteristics

Walsin Part Number	L(uH)	Toleran ce	Test Frequency	RDC Maximum (mΩ)		Rated Current	I sat Typical (A)	
			(KHz),1V	TYP.	MAX	Typical (A)	. ,	
WLPM505030M1R5LC	1.5	М	100	20.0	25.0	6.0	10.0	
WLPM505030M3R3LC	3.3	M	100	32.0	38.0	5.0	7.0	

TEST INSTRUMENT: CHROMA 16502 Yentech1320+Zentech3305

- (1). Test Freq: 100KHz, 1V
- (2). All test data is referenced to 25°C ambient.
- (3). Operating Temperature Range -25°C to +125°C.
- (4)Storage Temperature Range: -20°C ~+40°C (<60% R.H.).
- (5). Rated Current: DC current(A)that will cause an approximate △T of 40°C.
- (6). I sat: DC current(A)that will cause Lo to drop approximately 30%.
- (7). The part temperature (ambient +temp rise) should not exceed 125°C under worst case operating conditions.
- (8). Circuit design, component placement, PWB trace size and thickness, airflow and other cooling provisions all affect the part temperature Part temperature should be verified.
- (9).MSL: Level 1



RELIABILITY PERFORMANCE

Reliability Experiment For Electrical

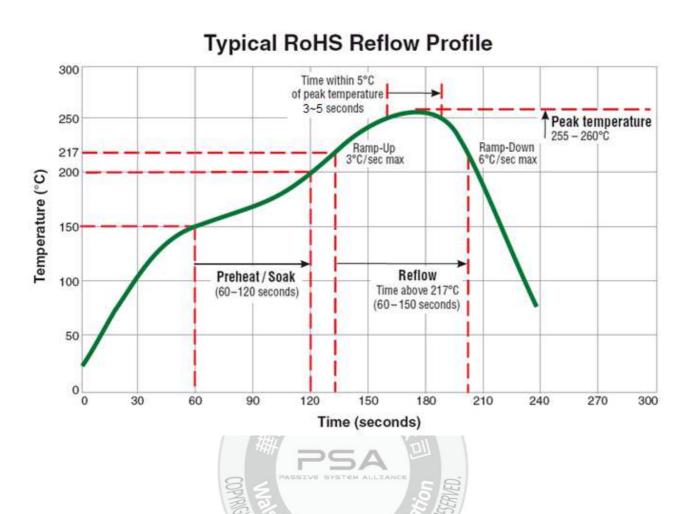
Test Item	Accept criteria	Test Condition	Standard Source
Humidity Test	1.Change from an initial value L:within±5% 2.no visible damage.	$+40^{\circ}\text{C} \pm 2^{\circ}\text{C}$, humidity of 90% $\pm 5\%$ (total 96 hours).	MIL-STD-202G Method 103B Test Condition B
High Temperature Test	1.Change from an initial value L:within±5% 2.no visible damage.	1.Temperature: +125°C ±2°C. 2.Test time: 48±2hrs.	IEC 68-2 Test Condition B
Low Temperature Test	1.Change from an initial value L:within±5% 2.no visible damage.	1.Temperature: -25°C±2°C. 2.Test time: 48±2hrs.	IEC 68-2 Test Condition A
Thermal Shock	1.Change from an initial value L:within±5% 2.no visible damage.	+125°C±5°C (30 minutes) ~ -55±5°C (30 minutes), temperature switch time: 5 minutes (total 50 cycles) Wind speeds 10m/sec.	Reference MIL-STD-202G Method 107G Test Condition A-2
Life Test	1.Change from an initial value L:within±5% 2.no visible damage.	+70°C±5°C (250Hours).	Reference MIL-STD-202G Method 108A Test Condition B

Reliability Experiment For Physical

Test Item	Accept criteria	Test Condition	Standard Source
Vibration Test	L:within±5%	10-55-10HZ, amplitude: 1.5mm, direction: X, Y, Z axes, each axis 2 hours (total 6 hours).	MIL-STD-202G Method 201A
Solder Heat Resistance Test	1.no visible damage.	255°C ~260°C for 3~5 Sec. in air,	Reference MIL-STD-202G Method 210F Test Condition K (Reflow)
Solder Ability Test	1. Lead must have 95% above coverage.	Soak in 245℃ solder pot of 3~5 Sec.	Reference J-STD-002D

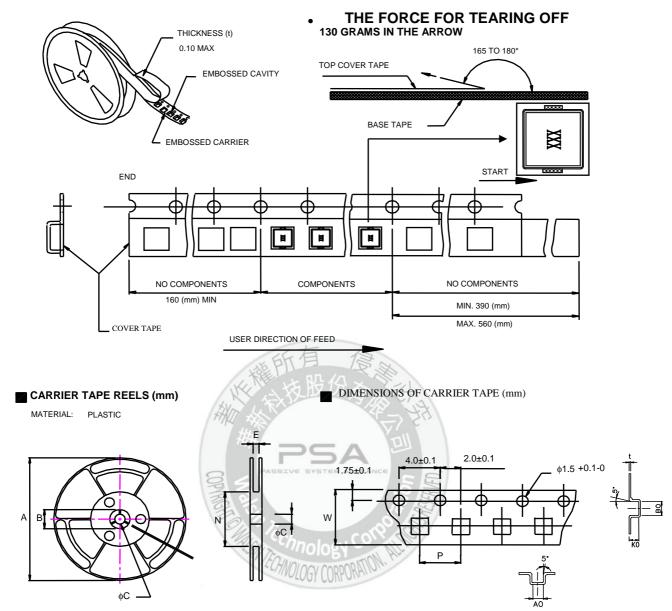


TYPICAL RoHS REFLOW PROFILE





Packaging



¾ 10 sprocket hole pitch cumulative tolerance ±0.20

UNIT : mm

	Α	В	С	Е	N	Р	W	t	A0	В0	K0
DIM.	330	25.0	13.0	12.5	100	8.0	12.0	0.4	5.7	5.9	3.6
TOL.	±0.2	±0.5	±0.5	±0.5	MIN	±0.1	±0.3	±0.05	±0.1	±0.1	±0.1

Quantity per reel: 2K pcs